

New Product Introduction April 2026



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[EVAL_65WT1_FF_502LD for CoolSET™ ICE502LD PWM FF Gen5 Pro and CoolSiC™ 1700 V MOSFET](#)

[KIT_CSK_BGT60CUTR13, XENSIV™ connected sensor kit with XENSIV™ BGT60CUTR13AIP CMOS 60 GHz radar sensor](#)

[REF_Audio_GaNb_750W_750 W class D audio amplifier evaluation board](#)

[REF-10KW3LNPC2Q power conversion reference design for inverter stages](#)

[REF-15KW2LBOOST power conversion reference design for converter stages](#)

PLATFORMS

[AURIX™ DRIVECORE AUTOSAR \[Infineon, Elektrobit, TASKING\]](#)

[PSOC™ DRIVECORE Smart End Point \[Infineon, Elektrobit, IAR\]](#)

TOOLS

[ModusToolbox™ Power Suite - Power Conversion Simplified](#)

CoolSET™ ICE501XD and ICE502XD PWM FF Gen5 Pro

The ICE501XD and ICE502XD CoolSET™ PWM FF Gen5 Pro are the latest Fixed Frequency PWM controller optimized for off-line switch mode power supply in cascode configuration and configurable gate clamp voltage for driving CoolSiC™ or CoolMOS™ MOSFET. The cascode configuration helps to achieve a fast startup time and avoid lossy startup resistor. The frequency reduction with frequency jitter operation offers low EMI and better efficiency across the load range. The product has a wide operating range (12.5 V ~ 29 V) of IC power supply and lower power consumption. The numerous protection functions together with line overvoltage protection can make the power supply system operate in a robust condition. All these make the PWM FF Gen5 Pro an outstanding PWM controller for fixed frequency flyback converter in the market.



Features

- > 65 kHz and 100 kHz maximum switching frequency
- > Active Burst Mode for low stand-by power
- > Selectable gate voltage 10 V, 15 V and 18 V
- > Frequency jitter for low EMI
- > Integrated error amplifier
- > Comprehensive protection with line OVP

Benefits

- > Reduced BOM
- > Good light load efficiency
- > Slope compensation for CCM operation

Competitive advantage

- > Selectable gate voltage 10 V, 15 V and 18 V for driving external power MOSFET
- > Comprehensive protections, including input line overvoltage protection
- > Fast startup by V_{CC} charging via external CoolSiC™ / CoolMOS™
- > Integrated soft-start to minimize component stress during startup
- > Integrated error amplifier to support direct sense for non-isolated design

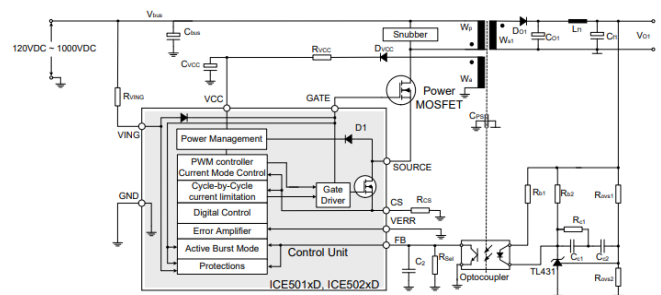
Target applications

- > Battery energy storage (BESS)
- > Uninterruptible Power Supply (UPS)
- > EV charging
- > General purpose motor drive
- > 3-phase string inverter solutions

Product collaterals / Online support

[Product page](#)

Block diagram

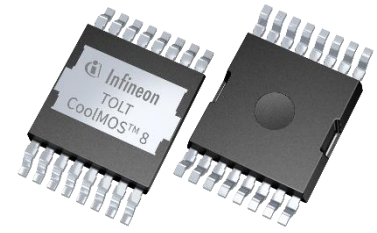


Product overview incl. datasheet link

OPN	SP Number	Package
ICE501LDXTMA1	SP006158560	PG-DSO-8
ICE502LDXTMA1	SP006158548	PG-DSO-8
ICE501MDXTMA1	SP006158566	PG-DSO-8
ICE502MDXTMA1	SP006158556	PG-DSO-8

CoolMOS™ 8 MOSFET 600 V in TOLT package

Built on Infineon's world-class super-junction MOSFET platform with an integrated fast body diode, making it suitable for a wide range of applications. The 600 V CoolMOS™ 8 enables the highest power density and superior reliability at the lowest possible system cost. It is enhancing Infineon's WBG offering and the successor of the 600 V CoolMOS™ 7 MOSFET family.



Features

- > Significant reduction of losses
- > Excellent commutation ruggedness
- > Integrated fast body diode
- > ESD protection
- > .XT interconnection technology
- > For hard and soft switching applications

Competitive advantage

- > Integrated fast body diode
- > .XT interconnect technology
- > Simplified product portfolio
- > Ease of use and shorter design in cycle

Benefits

- > Increased power density
- > Ease of use and shorter design in cycle
- > Best price-performance
- > Reduces the size of system
- > Enable multiple topologies
- > Improved thermal performance

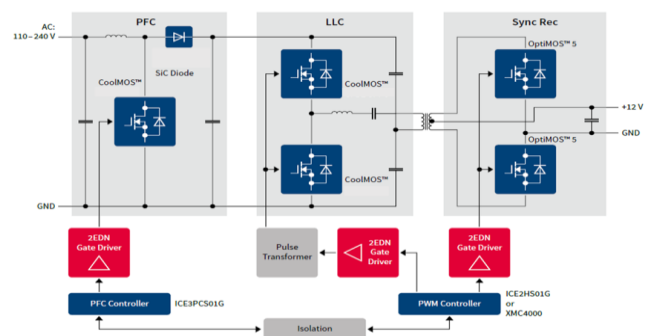
Target applications

- > [Datacenter](#)
- > [Server Telecom](#)
- > [Industrial SMPS](#)
- > [Energy Storage](#)
- > [EV Charging](#)
- > [TV](#)
- > [Charger and adapter](#)
- > [LEV](#)

Product collaterals / Online support

[Product family page](#)

Block diagram

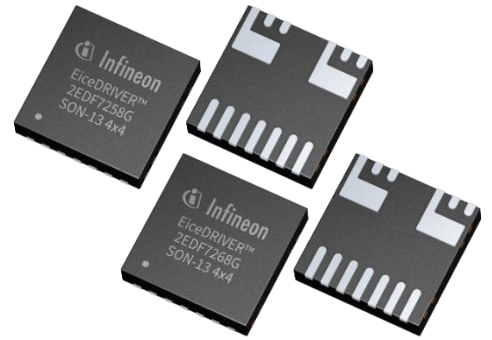


Product overview incl. datasheet link

OPN	SP Number	Package
IPLT60R024CM8XTMA1	SP006161994	PG-HDSOP-16
IPLT60R037CM8XTMA1	SP006161997	PG-HDSOP-16
IPLT60R055CM8XTMA1	SP006162000	PG-HDSOP-16
IPLT60R070CM8XTMA1	SP006162003	PG-HDSOP-16
IPLT60R099CM8XTMA1	SP006162006	PG-HDSOP-16

EiceDRIVER™ 2EDF72x8G Isolated gate driver IC

The EiceDRIVER™ 2EDF72x8G is dual channel isolated gate driver ICs with floating outputs. This strong 5 A/9 A source/sink dual channel gate driver comes with a high 100 V/ns CMTI (common mode transient immunity) for robust operation with MOSFETs and GaN HEMTs in high-power switching noise environments. The 2EDF72x8G is available in a 13-pin VSON 4x4 mm package with exposed pads, delivering a compact footprint with strong thermal performance.



Features

- > Dual Channel Isolated Gate Driver
- > 300 V_{rms} input-to-output isolation
- > Robust 100 V/ns CMTI
- > Strong 5 A / 9 A output stage
- > Short propagation delay of 38ns
- > +9 / -5ns in-out prop. delay accuracy
- > < 2 us UVLO recovery time
- > 1.2 V Output clamping threshold

Benefits

- > Compact and thermally capable solution
- > Robust isolation
- > Tight timing for increased efficiency
- > Reliable at high switching frequencies

Competitive advantage

- > PMOS source increases turn-on efficiency
- > Robust CMTI provided by coreless transformer isolation

Target applications

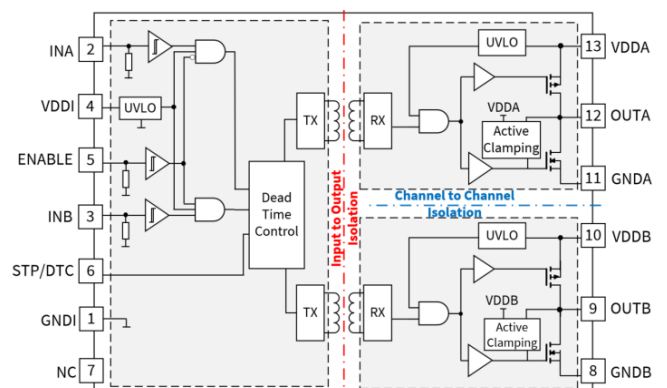
- > [DC-DC power conversion for telecommunications infrastructure](#)
- > [Microinverter solutions](#)
- > [Power optimizer solutions](#)
- > [Industrial power supplies](#)
- > [Power tools](#)
- > [Low-voltage drives](#)

Product collaterals / Online support

[Product page: 2EDF7258G](#)

[Product page: 2EDF7268G](#)

Block diagram



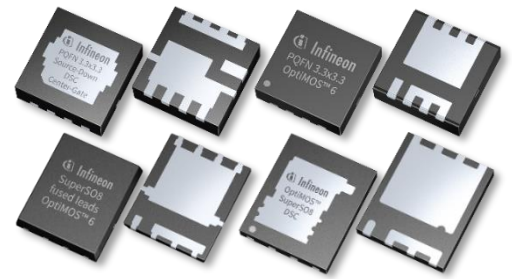
Product overview incl. datasheet link

OPN	SP Number	Package
2EDF7258GXTMA1	SP006011187	PG-VSON-13
2EDF7268GXTMA1	SP006037688	PG-VSON-13

OptiMOS™ 6 60 V next-generation MOSFET platform

OptiMOS™ 6 60 V is the latest power MOSFET technology, setting the new industry standard for benchmark performance.

Compared to its predecessor, OptiMOS™ 5, Infineon's latest wafer technology offers significant performance improvement, including > 37% lower $R_{DS(on)}$ and ~25% improved $FOM_{Qg} \times R_{DS(on)}$. These improvements lead to higher system efficiency and power density in soft-switching topologies and low-frequency applications.



Features

- > > 37% less $R_{DS(on)}$ vs OptiMOS™ 5 in SuperSO8
- > High-performance silicon technology
- > 175°C rated
- > Industrial qualification
- > Ideal for soft-switching applications

Benefits

- > Lower conduction losses than OptiMOS™ 5
- > Lower switching losses than OptiMOS™ 5
- > Improved performance efficiency
- > Superior power handling capability
- > Robust reliable performance

Product collaterals / Online support

[Product family page](#)

Target applications

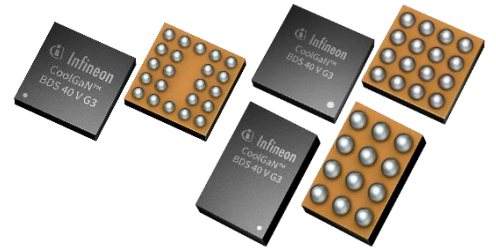
- > DC-DC Power Conversion
- > Server Power Supply Units
- > Telecom Infrastructure
- > Battery Management Systems
- > Low-Frequency Drives

Product overview incl. datasheet link

OPN	SP Number	Package
ISC009N06NM6ATMA1	SP005570342	PG-TDSON-8
ISC060N06NM6ATMA1	SP005570793	PG-TDSON-8
ISZ025N06NM6ATMA1	SP006010851	PG-TSDSON-8
IQE018N06NM6ATMA1	SP005741171	PG-TSON-8
IQE018N06NM6CGATMA1	SP005741181	PG-TTFN-9
IQE018N06NM6CGSCATMA1	SP005741184	PG-WHTFN-9
IQE018N06NM6SCATMA1	SP005741178	PG-WHSON-8

CoolGaN™ Bidirectional Switch 40 V G3

The CoolGaN™ Bidirectional Switches 40 V G3 are normally-off bidirectional power transistors housed in a small WLCSP packages, enabling high power density designs. Thanks to their very low on-state resistance, they are the ideal choice for reliable performance in demanding applications that require bidirectional blocking, such as load switches.



Features

- > 40 V bidirectional e-mode transistor
- > Drain-to-drain configuration
- > Bidirectional blocking capability
- > Low gate charge, low output charge
- > Qualified according to JEDEC

Benefits

- > Enabling smaller designs
- > Reducing power losses
- > Lowers system cost

Competitive advantage

- > Enables up to 4x smaller device size
- > Supports significant PCB size and weight reduction
- > Diverse application space

Target applications

- > [Mobile devices and smartphone solutions](#)
- > [Power conversion](#)
- > [Battery management systems](#)

Product collaterals / Online support

[Product page: IGK080B041SXTSA1](#)

[Product page: IGK048B041SXTSA1](#)

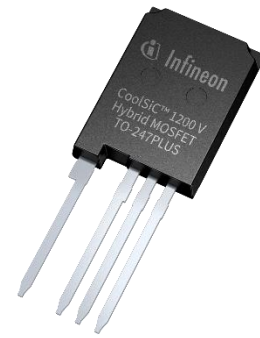
[Product page: IGK120B041SXTSA1](#)

Product overview incl. datasheet link

OPN	SP Number	Package
IGK048B041SXTSA1	SP006153012	SG-UFWLB-22
IGK080B041SXTSA1	SP006152840	SG-UFWLB-16
IGK120B041SXTSA1	SP006153109	SG-UFWLB-12

CoolSiC™ MOSFET 1200 V Hybrid - TO-247PLUS 4pin

The CoolSiC™ MOSFET 1200 V Hybrid Discrete G2, housed in a TO-247 4-pin package, combines the advanced capabilities of Generation 2 MOSFET technology with a Soft-Switching 1200 V, Emitter-Controlled 7 Silicon Diode. Designed specifically for solar MPPT stages, this innovative solution delivers enhanced performance for compact, reliable, and cost-optimized systems.



Features

- > $R_{DS(on)} = 18$ and 36 m Ω at $V_{GS} = 18$ V, $T_{vj} = 25^{\circ}\text{C}$
- > Reverse-polarity protection diode
- > Diode $I_F = 50$ and 75 A at $T_c = 100^{\circ}\text{C}$
- > Very low switching losses
- > Benchmark gate threshold voltage 4.2 V
- > Robust against parasitic turn on

Benefits

- > Popular package, seamless transition from IGBT or SiC MOS
- > Better energy efficiency
- > Optimized performance
- > Ease of use

Competitive advantage

- > Highly reliable
- > Higher power density
- > Integrated reverse-polarity protection diode

Target applications

- > String inverter

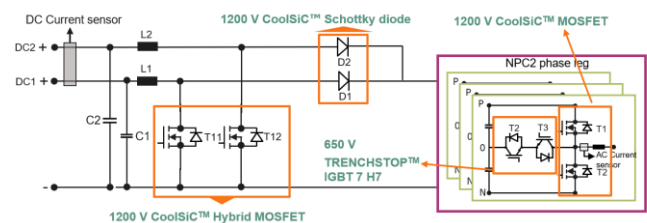
Product collaterals / Online support

[Product page: IMY120R036CM2H](#)

[Product page: MY120R036AM2H](#)

[Product page: MY120R018CM2H](#)

Block diagram

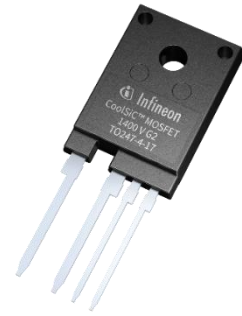


Product overview incl. datasheet link

OPN	SP Number	Package
IMY120R036CM2HXKSA1	SP006113063	PG-TO247-4
IMY120R018CM2HXKSA1	SP006124239	PG-TO247-4
IMY120R036AM2HXKSA1	SP006124242	PG-TO247-4

CoolSiC™ MOSFET discrete 1400 V in TO-247 4-pin portfolio extension

CoolSiC™ MOSFET discrete 1400 V G2 in TO-247 4-pin combines cutting-edge SiC technology with robust high-creepage package. It enables designs with bus voltages beyond 1000 V. For existing applications, it offers both additional voltage margin and enhanced reliability. Furthermore, it allows increased switching speed, leading to higher efficiency. Pin-to-pin compatible, it is suitable for PV, EV charging, ESS and many other industrial applications.



Features

- > $V_{DSS} = 1400 \text{ V}$ at $T_{vj} = 25^\circ\text{C}$
- > $R_{DS(on)} = 11 \text{ m}\Omega$ at $V_{GS} = 18 \text{ V}$, $T_{vj} = 25^\circ\text{C}$
- > Very low switching losses for efficiency
- > Short circuit withstand time of $2 \mu\text{s}$
- > Wider max V_{GS} range from -10 V to $+25 \text{ V}$
- > Benchmark gate threshold voltage 4.2 V

Benefits

- > Higher power density
- > Improved overall system efficiency
- > Increased system output power
- > Enhanced cooling optimization
- > Ease of system design
- > Robustness against transient overloads
- > Robustness against avalanche conditions
- > Robustness against Miller effect

Competitive advantage

- > Enabling designs $>1000 \text{ V}$
- > Very reliable package with high creepage
- > Robustness against transient overloads
- > For applications with an upper limit of 1000 volts: sufficient voltage margins for faster switching at high peak currents
- > Its high-power density allows reducing the overall system size

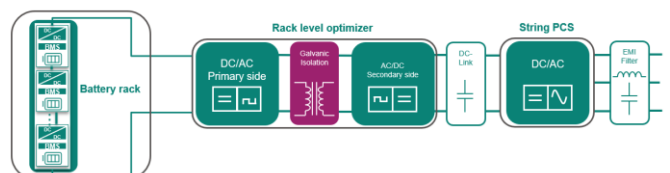
Target applications

- > Energy Storage Systems
- > EV Charging
- > Solar
- > UPS

Product collaterals / Online support

[Product page](#)

Block diagram

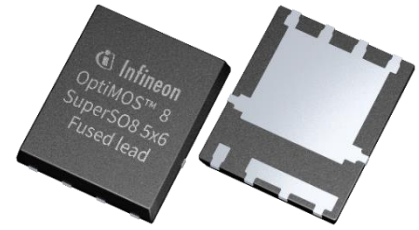


Product overview incl. datasheet link

OPN	SP Number	Package
IMZC140R011M2HXKSA1	SP006073593	PG-TO247-4

OptiMOS™ 8 ISC016N08NM8 n-channel power MOSFET 80 V in SuperSO8

This OptiMOS™ 8 is a normal level 80 V MOSFET in SuperSO8 packaging with 1.6 mOhm on-resistance.



Features

- > Very low on-resistance
- > High current carrying capability
- > Industrial qual for optimum reliability
- > Industry-standard footprint

Benefits

- > Low conduction losses
- > Highest efficiency and power density
- > High system reliability
- > Thermal robustness

Competitive advantage

- > Very low $R_{DS(on)}$
- > Good price/performance ratio
- > High-efficiency MOSFET technology

Target applications

- > [Data center and AI data center solutions](#)
- > [Telecommunications infrastructure](#)
- > [Industrial and consumer BMS](#)
- > [Server power supply units \(PSU\)](#)
- > [Cordless power tools and outdoor power equipment](#)

Product collaterals / Online support

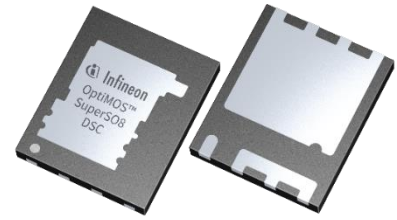
[Product page](#)

Product overview incl. datasheet link

OPN	SP Number	Package
ISC016N08NM8ATMA1	SP006165693	PG-TDSON-8

OptiMOS™ 8 ISC016N08NM8SC n-channel power MOSFET 80 V in SuperSO8 DSC package with dual-side cooling (DSC)

The OptiMOS™ 8 power MOSFET in SuperSO8 DSC (dual-side cooling) package offers all thermal management benefits of dual-side cooling solutions with an industry-standard footprint.



Features

- > Very low on-resistance
- > Improved thermal performance
- > High current carrying capability
- > Compatible with PQFN 5x6

Benefits

- > Minimized conduction losses
- > Less device paralleling required
- > Highest efficiency and power density
- > Thermal robustness

Competitive advantage

- > Very low $R_{DS(on)}$
- > Improved thermal performance
- > High-efficiency MOSFET technology

Target applications

- > [Data center and AI data center solutions](#)
- > [Telecommunications infrastructure](#)
- > [Industrial and consumer BMS](#)
- > [Server power supply units \(PSU\)](#)

Product collaterals / Online support

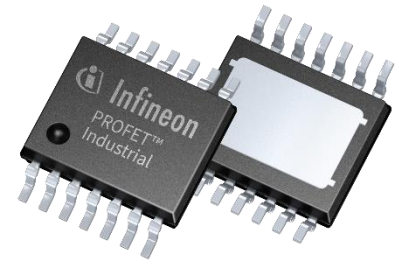
[Product page](#)

Product overview incl. datasheet link

OPN	SP Number	Package
ISC016N08NM8SCATMA1	SP006195339	PG-WSON-8

PROFET™ Industrial smart high-side switch

Infineon's PROFET™ Industrial smart high-side switches offer robust and reliable high-voltage solutions for industrial applications. They can switch all types of resistive, inductive and capacitive loads, as well as higher inductive loads and drive relays smoothly. Our switches are perfect for replacing electromechanical relays, fuses, and discrete circuits.



Our latest PROFET™ Industrial devices:

ITS6035S-EP-K
ITS6080S-EP-D
ITS4035S-EP-D
ITS4080S-EP-D

Features

- Supply voltage tolerance up to 60 V
 - Load current range up to 7 A
 - $R_{DS(ON)}$ range type: 35 mOhm – 130 mOhm
- 1/2/4 channel devices
- Wide output current range
- Digital Diagnostic via status pin (fully featured devices)
- Synchronized discharge functionality
- Analog current sense pin
- Open load diagnosis

Competitive advantage

- > User adjustable current limitation
- > Overvoltage lockout for 60 V version
- > 24 V control inputs compatible to 3.3 V and 5 V logic levels
- > Supply voltage tolerance up to 60 V for ITS60xxx-EP

Benefits

- > Devices with user adjustable current limitation ranging from 3 A to 13.2 A
- > Devices with Overvoltage lockout function (60 V)
- > Enhanced short circuit operation
- > Faster failure detection (Dedicated STATUS pin)
- > PCB space savings due to small packages and best-in class $R_{DS(ON)}$

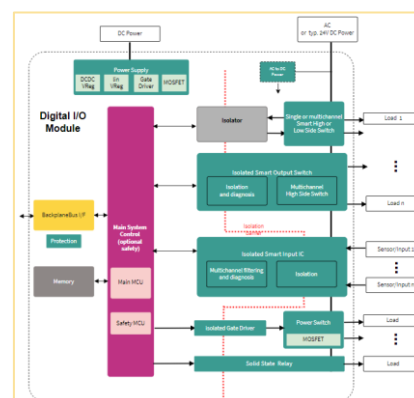
Target applications

- > PLC (Programmable Logic Controller)
- > Digital IO modules
- > Heating
- > Variable value control
- > Load control and self-protection
- > Relay

Product collaterals / Online support

[Product family page](#)

Block diagram

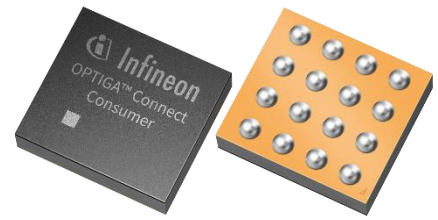


Product overview incl. datasheet link

OPN	SP Number	Package
ITS6035SEPKXUMA1	SP005858659	PG-TSDSO-14
ITS6080SEPDUMA1	SP004264566	PG-TSDSO-14
ITS4035SEPDUMA1	SP005073078	PG-TSDSO-14
ITS4080SEPDUMA1	SP005073090	PG-TSDSO-14

OPTIGA™ Connect Consumer OC1230

OPTIGA™ Connect Consumer OC1230 is the world's smallest GSMA-compliant 28 nm eSIM, optimized for devices like smartwatches and wearables. Its ultra-small chip-scale package (1.8 x 1.6 x 0.4 mm) saves PCB space, while 25% better performance-to-power ratio extends battery life. It supports 5G, remote SIM provisioning, multiple profiles, and global deployment with a single SKU. Ideal for seamless connectivity and high efficiency.



OPTIGA™ Connect Consumer is available under NDA.

Features

- > Global eSIM service interoperability
- > RSP and MEP GSMA SGP. 22 v3 compliant
- > SOTA/OS patching
- > Certified to CC EAL 6 +
- > Voltage classes: C (1.8 V), D (1.2 V)
- > Interfaces: ISO7816, SPI
- > WLCSP (1.8 x 1.6 x 0.4 mm) package
- > X2QFN20 (3.0 x 3.0 x 0.3 mm) package

Competitive advantage

- > OC1230 offers 1MB user free memory supporting additional applications (e.g. Keymint, eID) and offers user sufficient user free memory for MNO profiles and data
- > OC1230 is the smallest eSIM on the market with 3mm² footprint in CSP form factor
- > OC1230 is the first eSIM that supports 1.2 V (SWP=1.8 V) supply voltage which is targeted by modem makers (e.g. Qualcomm) and OEMs to reduce power consumption
- > OC1230 is based on SLC21 (CC EAL6+, PQC ready) and much newer and safer than competitor devices (e.g. ST33K, ST33J)

Product collaterals / Online support

[Product page](#)

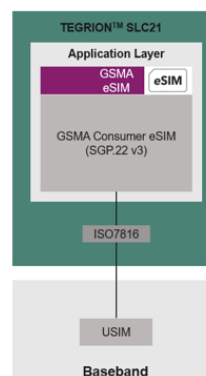
Benefits

- > World's tiniest (28nm) GSMA-compliant eSIM
- > Easy integration
- > Full interoperability
- > 25% better performance / power ratio
- > Extended battery lifetime
- > Future-proof security platform
- > Rich new features: e.g. OS patching, MEP
- > Post-quantum cryptography (PQC) ready

Target applications

- > Smartphones
- > Tablets
- > Smart Watches
- > Laptops
- > Cellular Routers
- > POS Terminals
- > Consumer IoT Devices

Block diagram

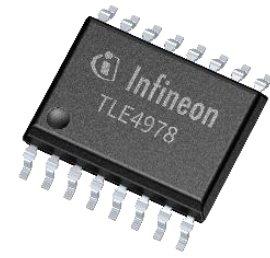


Product overview incl. datasheet link

OPN	SP Number	Package
OC12301015WLB16XTMA9	SP006272029	SG-XFWLB-16
OC12301015X2QFNXTMA5	SP006272041	PG-X2QFN-20

XENSIV™ TLE4978 coreless magnetic current sensor, 5 V for On-Board Charger, PV inverter, AI datacenter

XENSIV™ TLE4978 highly precise coreless current sensor is designed with the hybrid Hall + coil architecture. It delivers bi-directional AC/DC measurements with simultaneous over-current and zero-crossing detection (OCD and ZCD). Developed in accordance with ISO 26262 for safety requirements rated up to ASIL-B, its high 9 MHz bandwidth offers exceptional accuracy, low noise (typ. 38 mARMS), minimal sensitivity error over temperature and lifetime (max. $\pm 1.2\%$), and low offset error over temperature and lifetime (max. 200 mA).



Features

- > High bandwidth of 9 MHz
- > Current measurement from 45 A to 67.5 A
- > Supply voltage: 5 V
- > 100 ns response overcurrent detection
- > 80 ns delay zero-crossing detection
- > Operating ambient temperature: -40°C to 150°C (Grade 0)
- > ASIL-B-classified
- > DSO-16 300 mil package with basic isolation and reinforced isolation

Benefits

- > High versatility for different power ranges, with OCD and ZCD programming capabilities
- > High bandwidth, enabling use across applications
- > Highly precise measurement over temperature and lifetime
- > Exceptional low-current measurement capabilities, thanks to low noise performance
- > Easy integration with pre-calibrated and pre-programmed sensitivity

Competitive advantage

- > High 9 MHz bandwidth with pre-programmed sensitivity
- > Exceptionally low noise (typ. 38 mARMS)
- > Minimal sensitivity error over temperature and lifetime (max. $\pm 1.2\%$)
- > Low offset error over temperature and lifetime (max. 200 mA)

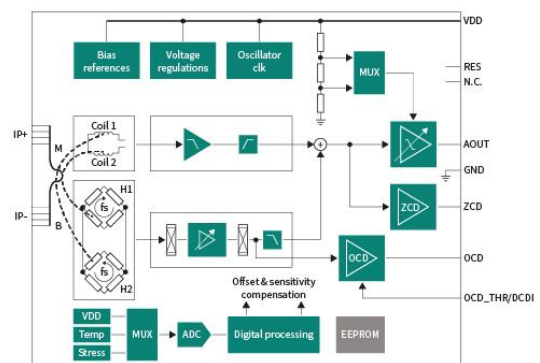
Target applications

- > On-Board Charger
- > EV charging
- > DCDC Converter
- > PV Inverter
- > AI data center

Product collaterals / Online support

[Product page](#)

Block diagram

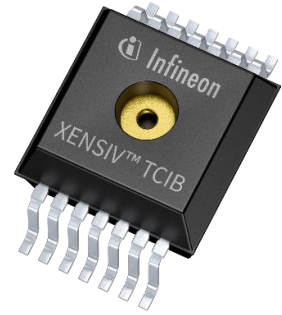


Product overview incl. datasheet link

OPN	SP Number	Package
TLE4978R040W5OS0010XUMA1	SP005858343	PG-DSO-16

XENSIV™ TCI-B: ASIL-B thermal conductivity H2 sensor for early thermal runaway detection

The XENSIV™ TCI-B gas sensor plays a crucial role in ensuring safety in battery packs for EVs and energy storage by enabling early detection of thermal conductivity changes caused by initial gas emissions, such as hydrogen and hydrocarbons, offering instant indication of thermal runaway, well before temperatures become critical. Its fast response enables proactive safety interventions, while immunity to poisoning ensures consistent, long-term protection.



Features

- > AEC-Q100 up to 105°C
- > Fast response time < 100 ms
- > Ultra-low current consumption
- > Robust and proven packages
- > Lifetime of 15 years with low drift
- > Power saving via autonomous mode
- > UL-2075 certified
- > FUSA QM/ASIL-B capable

Benefits

- > No maintenance or replacement costs
- > Robustness and stability
- > Low-power mode enabled by user
- > No recalibration needed in the field
- > Automotive grade sensor reliability
- > ISO26262 compliance up to ASIL-B

Competitive advantage

- > Lifetime of 15 years with low drift
- > Robustness and stability
- > Low-power mode enabled by user
- > No recalibration needed in the field

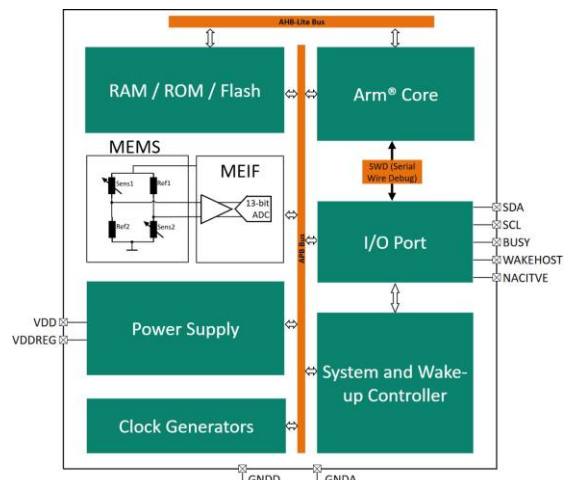
Target applications

- > [Automotive BMS](#)
- > [Automotive battery pack monitoring](#)
- > [Battery energy storage \(BESS\)](#)

Product collaterals / Online support

[Product page](#)

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
TCIBXTMA1	SP006101806	PG-DSOSP-14

XENSIV™ TCIR: A thermal conductivity-based sensor for A2L refrigerants leakage, with low power, fast response time and up to 15-years lifetime

The XENSIV™ TCI-R gas sensor detects leaks quickly and reliably by measuring changes in thermal conductivity specific to refrigerants like R32, R454A-B-C, R455A, R1234yf. Its fast response prevents compressor damage, loss of cooling efficiency, and regulatory noncompliance. Thanks to its low drift and resistance to cross-sensitivity or poisoning, it maintains accuracy over years of operation, reducing maintenance costs and environmental impact.



Features

- > AEC-Q100 up to 105°C
- > Fast response time < 5 s
- > Ultra-low current consumption
- > Robust and proven packages
- > Lifetime of 15 years with low drift
- > Power saving via autonomous mode
- > UL-60335-2-40/89 (construction review)

Benefits

- > No maintenance or replacement costs
- > Robustness and stability
- > Low-power mode enabled by user
- > No recalibration needed in the field

Competitive advantage

- > Fast response time < 5 s
- > Lifetime of 15 years with low drift
- > No maintenance or replacement costs

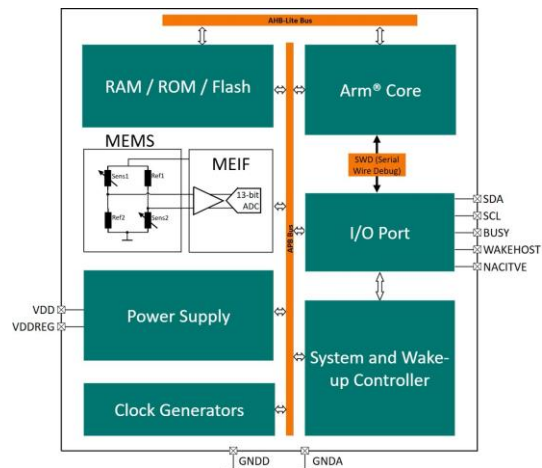
Target applications

- > [Heating ventilation and air conditioning \(HVAC\)](#)
- > [Residential air conditioning](#)
- > [Residential heat pumps](#)
- > [Commercial HVAC system](#)

Product collaterals / Online support

[Product page](#)

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
TCIRXTMA1	SP006185783	PG-DSOSP-14

XENSIV™ KP215E1701 Manifold Absolute Pressure

XENSIV™ compact analog MAP sensor with BiCMOS technology, offering high accuracy and reliability for automotive and industrial applications.

The KP215E1701 is a miniaturized analog MAP sensor based on the capacitive principle with BiCMOS technology and integrated signal conditioning. It converts 10-115 kPa pressure into a 0.4-4.65 V analog output. Encased in a "green" SMD package, it offers high accuracy and sensitivity, making it ideal for manifold air pressure monitoring in automotive, industrial, and consumer applications.



Features

- > High precision pressure sensing
- > Ratiometric analog output
- > Large operating temperature range
- > Broken wire detection
- > Internal voltage clamping thresholds
- > Eco-friendly 8 pin SMD housing
- > Automotive qualified AEC-Q100

Benefits

- > Wide 10–115 kPa suits manifold pressure
- > Analog output simplifies ECU integration
- > AEC-Q100 ensures automotive reliability
- > EEPROM calibration improves consistency

Competitive advantage

- > Improved accuracy of ± 1.4 kPa
- > Suitable for automotive, industrial and consumer applications
- > Enhanced drift over lifetime stability due to EEPROM calibration

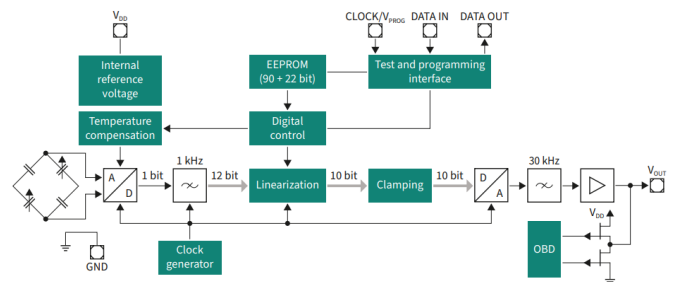
Target applications

- > Automotive applications (manifold air pressure measurement)
- > Industrial control
- > Consumer applications
- > Medical applications
- > Weather stations
- > Altimeters

Product collaterals / Online support

[Product page](#)

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
KP215E1701XTMA1	SP006201523	PG-DSOF-8

XENSIV™ KP215IGE1701 Manifold Absolute Pressure

XENSIV™ compact analog MAP sensor with increased protective gel (IG) for improved chemical robustness, offering high accuracy pressure sensing.

The KP215IGE1701 is a miniaturized analog MAP sensor utilizing a capacitive principle with BiCMOS technology, increased protective gel (IG), and an integrated signal conditioning circuit. It converts 10-115 kPa pressure into a 0.4-4.65 V analog output. Encased in a "green" SMD package, it delivers high accuracy and sensitivity, making it well-suited for manifold air pressure detection in automotive, industrial, and consumer applications.



Features

- > High precision pressure sensing
- > Ratiometric analog output
- > Large operating temperature range
- > Broken wire detection
- > Internal voltage clamping thresholds
- > Eco-friendly 8 pin SMD housing
- > Automotive qualified AEC-Q100
- > Increased protective gel

Benefits

- > Wide 10–115 kPa suits manifold pressure
- > Analog output simplifies ECU integration
- > AEC-Q100 ensures automotive reliability
- > EEPROM calibration improves consistency
- > Increased protective gel (IG) version for improved chemical robustness

Competitive advantage

- > Improved accuracy of ± 1.4 kPa
- > Suitable for automotive, industrial and consumer applications
- > Enhanced drift over lifetime stability due to EEPROM calibration
- > Improved chemical robustness

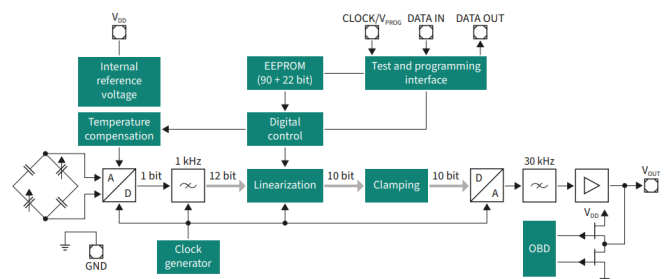
Target applications

- > Automotive applications (manifold air pressure measurement)
- > EGR (exhaust gas recirculation) in automotive applications
- > Industrial control
- > Consumer applications
- > Medical applications
- > Weather stations
- > Altimeters

Product collaterals / Online support

[Product page](#)

Block diagram

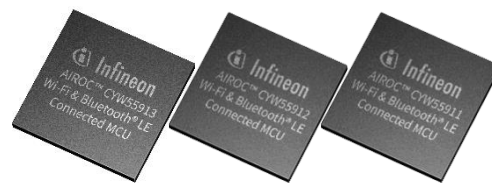


Product overview incl. datasheet link

OPN	SP Number	Package
KP215IGE1701XTMA1	SP006196878	PG-DSOF-8

AIROC™ CYW55913/2/1 Wi-Fi and Bluetooth® Connected MCU

The AIROC™- CYW55913/2/1 are a family of low-power, single-chip connected MCUs that support 1x1 single-stream, tri-band (CYW55913), dual-band (CYW55912) and single-band (CYW55911), Wi-Fi 6/6E, IEEE 802.11ax-compliant, supporting up to 1024 QAM (MCS11) in 20 MHz channels and Bluetooth® Low Energy 5.4. The devices integrate a 192 MHz Arm® Cortex®-M33 processor with Arm® TrustZone CC312, and include 768 KB of SRAM, with a QSPI interface for expanding FLASH and PSRAM with eExecute-in-place (XIP) and on-the-fly (OTF) encryption and decryption. The MCU supports multiple SDIO, I2C, SPI, UART, TCPWM, TDM/I2S, PDM, GPIOs, and 7-channel, 12-bit ADC. The devices are intended to be the primary MCU in the system, or to offload a host processor from Wi-Fi and networking functions thereby reducing BOM cost and space.



Features

- > MCU features: 192 MHz Arm® Cortex®- M33, PSA L2 with Arm® TrustZone CC312, QSPI for FLASH/PSRAM with XIP and OTF encryption and decryption, up to 48 GPIOs, SDIO, I2C, SPI, UART, TCPWM, TDM/I2S, PDM, ADC, embedded RTOS, Linux Host Driver and AT command set support
- > Wi-Fi/WLAN features: leading transmit power: +24 dBm, best in class sensitivity: -101.5 dBm, Wi-Fi 6/6E and Infineon range
- > Bluetooth® features: Bluetooth® LE 5.4, three output power paths optimized for best efficiency: +19/+13/+4 dBm, 111.5 dBm LE LR sensitivity, shared or dedicated Bluetooth® antenna for optimized coexistence with Wi-Fi and 802.15.4

Competitive advantage

- > CYW5591x supports Wi-Fi 6E enabling 6GHz band for clean spectrum, helping to improve the range
- > The CYW5591x transmit power of +24 dBm and sensitivity of -101.5 dBm is better than close competitors
- > Better RF performance, with its combination of transmit power (Tx), sensitivity, and low active power consumption in 6/6E GHz
- > Offers a simpler development path for most customers with the module offering from partners like Quectel, Ezurio, Azurewave and USI (that can support 2L and 4LC PTH PCBs)

Benefits

- > Integrated MCU reduces BOM cost and optimizes space
- > Seamless integration into ModusToolbox™
- > Optimized for IoT applications demands
- > Greenfield 6GHz band for expanded channels
- > Boosts network efficiency
- > Improves range and saves power
- > Bluetooth®/BLE Audio hosted or embedded modes
- > Multi-layer security for more protection

Target applications

- > Smart Home: Smart home, security cameras, door locks, thermostats, garage door openers, appliances, gateways, smart plug, vacuum cleaner, printer
- > Wearables: Smart watches, fitness bands
- > Industrial: Automated meter readers, payment systems, water heaters, boilers, inverters, HVAC, Body worn camera
- > Healthcare: CPAP Machines, defibrillation, healthcare wearable

Product collaterals / Online support

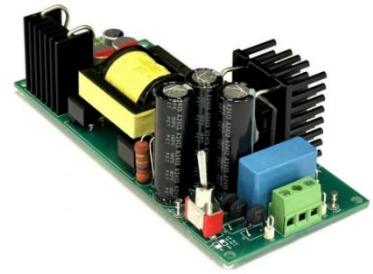
[Product family page](#)

Partners	Model	Device	Dimensions	Package	Antenna	Memory (Flash/PSRAM)	MP
Azurewave	AW-CU640	CYW55913	16 x 25 mm	LGA	PCB antenna	external	Now
Azurewave	AW-CU668	CYW55913	12 x 12 mm	LGA	RF Pad	external	Now
Azurewave	AW-CU642	CYW55912	16 x 25 mm	LGA	PCB antenna	external	Now
Azurewave	AW-CU680	CYW55912	12 x 12 mm	LGA	RF Pad	external	Now
Ezurio	IF913 (453-00400C/R)	CYW55913	7 x 11 mm	SMT	RF trace pin	external	Apr-26
Ezurio	IF913 (453-00401C/R)	CYW55913	7 x 11 mm	SMT	RF trace pin	Embedded 8MByte Flash +8Mbyte PSRAM	Apr-26
Ezurio	IF912 (453-00396C/R)	CYW55912	7 x 11 mm	SMT	RF trace pin	external	Apr-26
Ezurio	IF912 (453-00397C/R)	CYW55912	7 x 11 mm	SMT	RF trace pin	Embedded 8Mbyte Flash +8Mbyte PSRAM	Apr-26
Quectel	FGMC62N	CYW55912	13 x 16 mm	LGA	Ext Antenna	4MByte flash	Apr-26
Quectel	FGMC63N	CYW55913	13 x 16 mm	LGA	Ext Antenna	4MByte flash	Apr-26

For small volume opportunities please engage module partners

EVAL_100W1_FF_502MD for CoolSET™ ICE502MD PWM FF Gen5 Pro and CoolSiC™ 1700 V MOSFET

The EVAL_100W1_FF_502MD evaluation board is developed to support customers designing auxiliary power supplies for three-phase converters using CoolSET™ ICE502MD PWM Fixed Frequency Gen5 Pro controller and CoolSiC™ 1700 V MOSFET in a single-switch flyback topology. The board has a single output of +24 V with up to 100 W output power working in a wide input voltage range from 200 VDC to 1000 VDC.



Features

- > Externally selectable gate voltage of 10 V, 15 V, and 18 V
- > Fast startup through cascode configuration
- > Integrated error amplifier to implement primary side control, if required
- > Frequency reduction for improved light-load efficiency
- > Comprehensive protection including line overvoltage protection

Benefits

- > Reduced BOM
- > Good light load efficiency
- > Slope compensation for CCM operation

Product collaterals / Online support

[Board page](#)

Target applications

- > Home appliances
- > Telecommunications infrastructure
- > Renewables
- > Power conversion
- > Server power supply units (PSU)

Product overview incl. application notes link

OPN	SP Number	Package
EVAL100W1FF502MDTOBO1	SP006168102	-

EVAL_65WT1_FF_502LD for CoolSET™ ICE502LD PWM FF Gen5 Pro and CoolSiC™ 1700 V MOSFET

The EVAL_65WT1_FF_502LD evaluation board was developed to support customers designing auxiliary power supplies for three-phase converters using CoolSET™ ICE502LD PWM Fixed Frequency Gen5 Pro controller and CoolSiC™ 1700 V MOSFET in a single-switch flyback topology. The board has triple outputs (+12 V, +5 V, and -12 V) with up to 65 W output power working in a wide input voltage range from 200 VDC to 1000 VDC.



Features

- > Externally selectable gate voltage of 10 V, 15 V, and 18 V
- > Fast startup through cascode configuration
- > Integrated error amplifier to implement primary side control, if required
- > Frequency reduction for improved light-load efficiency
- > Comprehensive protection including line overvoltage protection

Benefits

- > Reduced BOM
- > Good light load efficiency
- > Slope compensation for CCM operation

Product collaterals / Online support

[Board page](#)

Target applications

- > Home appliances
- > Telecommunications infrastructure
- > Renewables
- > Power conversion
- > Server power supply units (PSU)

Product overview incl. application notes link

OPN	SP Number	Package
EVAL65WT1FF502LDTOBO1	SP006184396	-

REF_Audio_GaNb_750W 750 W class D audio amplifier evaluation board

The REF_Audio_GaNb_750W features the CoolGaN™ Transistors 100 V G3 combined with the MERUS™ IRS20957S class D audio driver ICs. This two-channel design is scalable up to 375 W x 2 channel at 2 Ω without a heatsink. The design includes all the required power supplies and connectors for ease of use and lab evaluation.



Features

- > 375 W x 2 channels: 10% THD+N, 2 Ω at ±36 V
- > 240 W x 2 channels: 10% THD+N, 4 Ω at ±40 V
- > Heatsinkless design
- > Overcurrent, overvoltage, and undervoltage protection
- > Overtemperature protection
- > Self-oscillating half-bridge topology
- > Onboard clock synchronization

Benefits

- > Superior power density with CoolGaN™
- > Clean switching performance
- > Narrow deadtime for better THD
- > Low residual noise 30 μV
- > IHF-A weighted, AES-17 filter
- > Easy to use
- > Compatible with MERUS™ driver

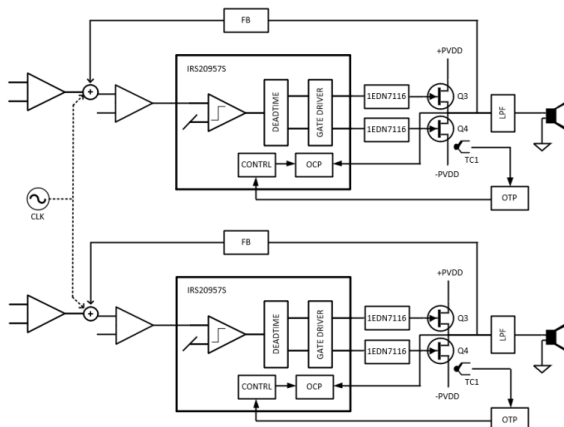
Product collaterals / Online support

[Board page](#)

Target applications

- > Audio amplifier

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
REFAUDIOGANB750WTOBO1	SP006156380	-

REF-10KW3LNPC2Q power conversion reference design for inverter stages

Compact and highly efficient NPC2 power conversion reference design for inverter stages with up to 10 kW.

Innovative combination of latest CoolSiC™ MOSFETs and QDPAK SMD package with top side cooling. High switching frequency of 48 kHz allows significant reduction of size and cost per kW. A separate XMC7200 based control card with closed loop control software and GUI is also available.



Features

- > Low loss 3-level NPC2 topology
- > Isolated gate driver card
- > Built-in aux power supply card
- > Large heatsink for passive cooling
- > Fans for high power ratings
- > Optional control card

Benefits

- > High peak efficiency 99.2 %
- > High switching frequency of 48 kHz
- > Up to 40 % shrinkage of filter size
- > No fans needed up to 10 kW
- > Fast and uncomplicated testing
- > Blueprint for fast prototyping

Competitive advantage

- > REF-10KW3LNPC2Q is a design blueprint to speed up any residential 3-phase string, hybrid and battery inverter project

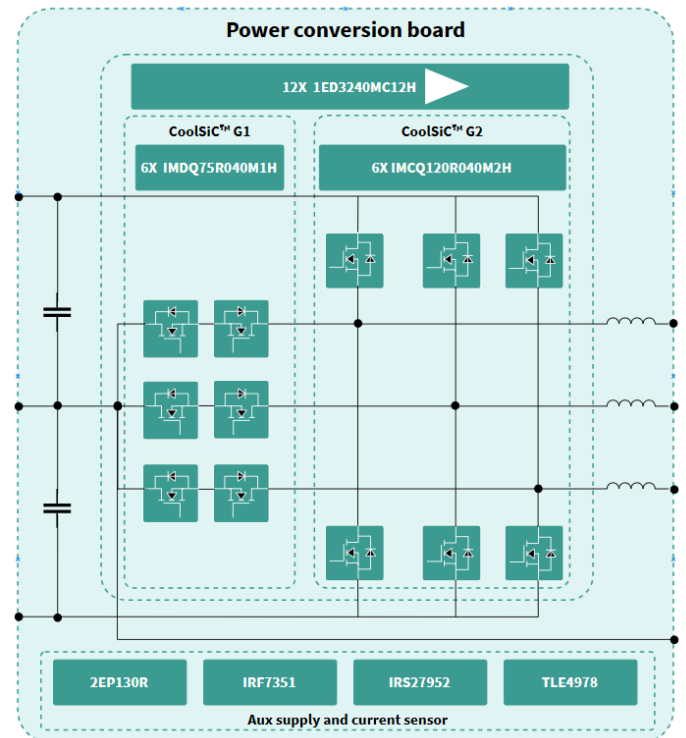
Target applications

- > [3-phase hybrid inverter solutions](#)
- > [3-phase string inverter solutions](#)

Product collaterals / Online support

[Board page](#)

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
REF10KW3LNPC2QTOBO1	SP006162553	--

REF-15KW2LBOOST power conversion reference design for converter stages

Power conversion reference design for the fast prototyping of PV boost converter stages with up to 15 kW and three independent DC input channels.

It features Infineon's latest 1200 V TRENCHSTOP™ IGBT 7 with best-fitting EiceDRIVER™ gate drivers and XENSIV current sensors in a modular design blueprint for 3-phase string and hybrid inverter projects.



Features

- > Modular design concept
- > Three independent boost converters
- > Isolated gate driver card
- > Current sensors for each DC input
- > Built-in aux power supply card
- > Large heatsink for passive cooling
- > Fans for high power ratings
- > Optional control card

Benefits

- > High peak efficiency > 98.8 %
- > High switching frequency of 24 kHz
- > Small size and lower cost per kW
- > No fans needed up to 10 kW
- > Fast and uncomplicated testing
- > Blueprint for fast prototyping

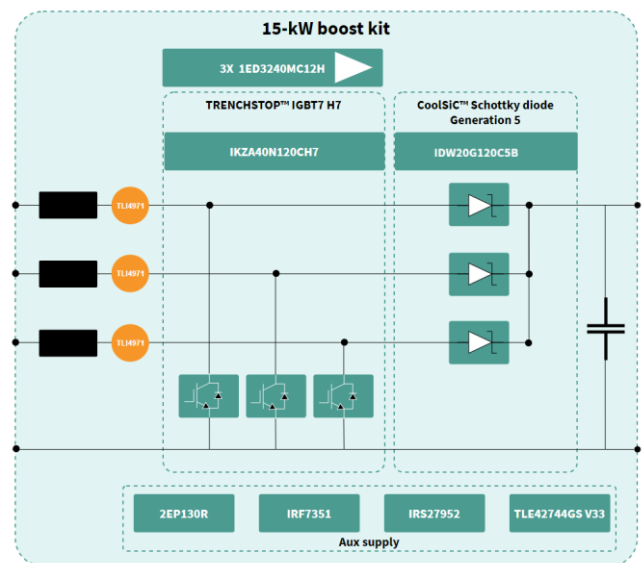
Product collaterals / Online support

[Board page](#)

Target applications

- > [3-phase hybrid inverter solutions](#)
- > [3-phase string inverter solutions](#)

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
REF15KW2LBOOSTTOBO1	SP006047580	--

AURIX™ DRIVECORE AUTOSAR [Infineon, Elektrobit, TASKING]

AURIX™ DRIVECORE AUTOSAR [Infineon, Elektrobit, TASKING] simplifies and accelerates the development of AUTOSAR-based ECU software projects, focusing on domain and zonal ECUs.

Running on Infineon's AURIX™ TC4Dx microcontroller, the bundle integrates Infineon's MCAL drivers with EB zoneo drivers for hardware acceleration, EB tresos AutoCore BSW, and TASKING's certified Compiler Tool Chain. It includes an AUTOSAR gateway demo.



Features

- > Full support of Infineon's HW accelerators
- > Pre-integrated EB tresos with EB GatewayCore and EB Zoneo
- > Multifunctional and simple tooling using EB tresos Studio and TASKING SmartCode C/C++ Compiler Tool Chain for TriCore and PPU

Benefits

- > Fast project start: Pre-integrated stack and fully integrated TASKING SmartCode C/C++ Compiler Tool Chain speeds up application development
- > Optimized execution: improved latency and CPU load due to SW optimization and HW offloading
- > Simple configuration: easy setup using EB tresos tooling for TC4x hardware accelerators

Competitive advantage

- > 3-Month Free Evaluation: Get started risk-free and explore the full potential of the bundle.
- > All-Inclusive Licensing: Includes all necessary licenses and tools, eliminating the need for complex supplier management and allowing you to start developing immediately.
- > Compatibility guaranteed: Ready-to-use, certified tooling for configuration, debugging, and compilation, ensuring a seamless development experience.

Target applications

- > Development of AUTOSAR-based ECU software projects on domain and zonal ECUs

Product collaterals / Online support

[Product page](#)

PSOC™ DRIVECORE Smart End Point [Infineon, Elektrobit, IAR]

This software bundle is designed to simplify and accelerate development for edge controllers and small peripheral ECUs in automotive subsystems. It focuses on cost efficiency, reusability, and extensibility.

The bundle integrates Elektrobit's EB tresos AutoCore Light, IAR's certified Arm toolchain and Infineon's qualified and certified low-level drivers, AutoPDL and microHAL.



Features

- > Resource optimized software platform: EB tresos AutoCore Light for small applications
- > Pre-integrated, qualified and certified drivers with EB tresos AutoCore OS for Cortex®-M0+ and AutoCore Light
- > IAR's certified toolchain for Arm
- > Infineon's qualified and certified low-level drivers: AutoPDL and microHAL

Benefits

- > Reliable on low-power MCUs with consistent performance in compact, cost-sensitive ECUs
- > Quick project setup and faster integration as startup package is available as pre-integrated solution
- > Build safe, compliant systems backed by ASIL-B and Cybersecurity Management System (CSMS) certifications, so you can focus on innovation
- > Confidence in compliance using IAR's certified toolchain, delivering optimized code size

Competitive advantage

- > 3-Month Free Evaluation: Get started risk-free and explore the full potential of the bundle
- > All-Inclusive Licensing: Includes all necessary licenses and tools, eliminating the need for complex supplier management and allowing you to start developing immediately
- > Compatibility guaranteed: Ready-to-use, certified tooling for configuration, debugging, and compilation, ensuring a seamless development experience

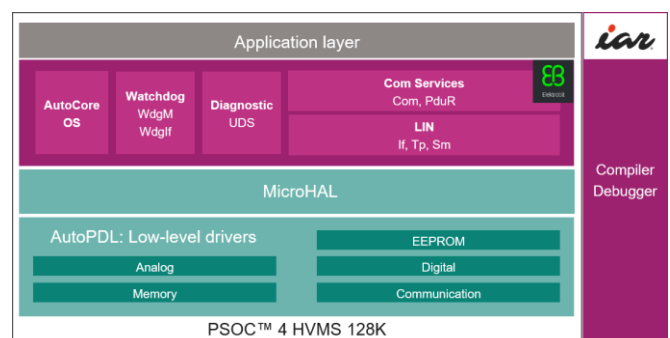
Target applications

- > Smart sensors
- > Interior lighting
- > Motor controls
- > Performance and resource optimized ECUs

Product collaterals / Online support

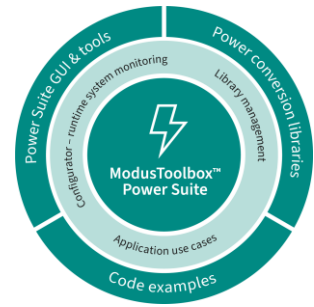
[Product page](#)

Block diagram



ModusToolbox™ Power Suite - Power Conversion Simplified

ModusToolbox™ Power Suite makes power conversion application development a breeze! With its user-friendly interface, you can easily develop, evaluate, and test power conversion solutions while enjoying real-time PMBUS monitoring. This suite offers comprehensive firmware and MCU configuration tools, along with advanced algorithms for peak performance, efficiency, and reliability. Plus, ModusToolbox™ integrates everything you need - peripheral drivers, middleware, configuration tools, visualization tools and code examples - into one powerful tool, streamlining your development process.



Features

- > Configure MCU for power conversion
- > GUI to simplify run-time lab testing including digital oscilloscope
- > Topology libraries supporting different power converters covering:
 - o Advanced control algorithms for different power topologies (PFC, LLC and more)
 - o Various filter options, like 3-Pole/ 3-Zero (3P3Z)
 - o Protection and housekeeping functions for optimal performance
- > Application-specific code examples that run on Infineon evaluation boards

Competitive advantage

- > Best in class microcontrollers for power conversion with future roadmap for greater portfolio
- > Easy to use Power Suite software brings down power conversion design complexities
- > Power Conversion ecosystem (power conversion libs supporting multiple power topologies, advanced power conversion algorithms, GUI tools, multiple evaluation kits, and code examples) for shorter time-to-market
- > Wide range of tools for improved solution evaluation including live debugging tools

Product collaterals / Online support

[Product page](#)

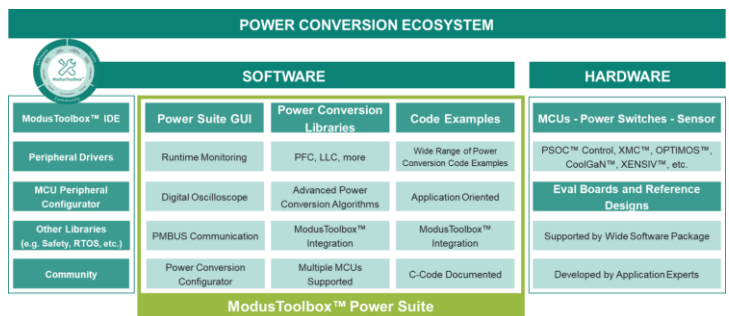
Benefits

- > Faster Time-to-Market: Enable developers to easily design, test, and optimize power conversion systems
- > Out-of-the-box solution
- > Comprehensive firmware and MCU configuration tools
- > Advanced algorithms tailored for optimal power stage performance, efficiency, and reliability
- > Fully integrated into ModusToolbox™: all the needed resources in a single tool

Target applications

- > Industrial power supplies
- > Server power supply units (PSU)
- > Telecommunications infrastructure SMPS and PSU
- > Server SMPS and PSU
- > Robotics
- > Solar and Micro Inverters
- > EV charging

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
KITPSC3PFC1TOBO1	SP006241996	LG-MADK-1
KITPSC3M5CC1	SP006051090	LG-MADK-1
KITPSC3M5DP1	SP006051088	LG-MADK-1